

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/17/2022

Details for "MAX3222IDW"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
MAX3222IDW	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	DW 20	7.52x12.82x2.35	616.6

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.102232	99.999022	999990	0.016581	166
Precious Metals	Silver	7440-22-4	0.000001	0.000978	10	0	0
Sub-Total			0.102233	100	1000000	0.016581	166
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.680571	79.999976	800000	0.110381	1104
Thermoplastics	Epoxy	85954-11-6	0.170143	20.000024	200000	0.027595	276
Sub-Total			0.850714	100	1000000	0.137976	1380
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	169.729591	97.585	975850	27.528208	275282
Copper and Its Alloys	Iron	7439-89-6	4.00039	2.3	23000	0.648818	6488
Copper and Its Alloys	Phosphorus	7723-14-0	0.02609	0.015	150	0.004232	42
Zinc and Its Alloys	Zinc	7440-66-6	0.17393	0.1	1000	0.028209	282
Sub-Total			173.930001	100	1000000	28.209467	282095
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.131266	95.12029	951203	0.02129	213
Precious Metals	Gold	7440-57-5	0.001076	0.77971	7797	0.000175	2
Precious Metals	Palladium	7440-05-3	0.005658	4.1	41000	0.000918	9
Sub-Total			0.138	100	1000000	0.022382	224
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	386.112311	88	880000	62.623022	626230
Other Plastics and Rubber	Carbon Black	1333-86-4	1.316292	0.3	3000	0.213488	2135
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	2.413202	0.55	5500	0.391394	3914
Thermoplastics	Epoxy	85954-11-6	48.922185	11.15	111500	7.934622	79346
Sub-Total			438.76399	100	1000000	71.162526	711625
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.781136	100	1000000	0.451069	4511
Sub-Total			2.781136	100	1000000	0.451069	4511
Total			616.566074			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, see Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/eoinfo
 Created on: 05/17/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS7098 low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.